Unit: mm

MA3XD11

Silicon epitaxial planar type

For high frequency rectification

Features

- Forward current (Average) $I_{F(AV)} = 1$ A rectification is possible
- \bullet Low forward voltage $V_{\rm F}$

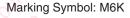
		0.16 ^{+0.10}
2		0, 0, 0, 0, 0, 0, 0, 0, 0, 0, 0, 0, 0, 0
	(0.95) (0.95) (1.9:0.1 2.90 ^{+0.05}	S.
		Sec.
	0 00 00	1: Anode 2: N.C. 3: Cathode
	EIAJ: SC-59	Mini3-G1 Package

Absolute Maximum Ratings $T_a = 25^{\circ}C$

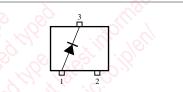
Parameter	Symbol	Rating	Unit
Reverse voltage	VR	20	V
Repetitive peak reverse voltage	V _{RRM}	25	V
Forward current (Average) *1	I _{F(AV)}	1.0	A
Non-repetitive peak forward surge current *2	I _{FSM}	3	А
Junction temperature	Tj	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note) *1: Mounted on an alumina PC board

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Internal Connection



Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

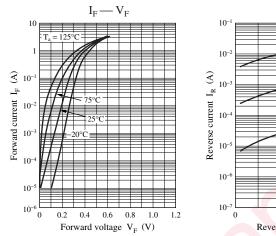
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	I _F = 1.0 A	20		0.45	V
Reverse current	I _R	$V_R = 20 V$			200	μΑ
Terminal capacitance	C Ct	$V_R = 0 V, f = 1 MHz$		180		pF

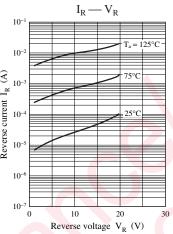
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

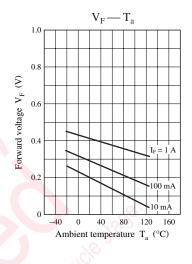
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 400 MHz.

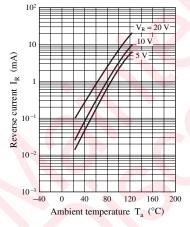
Panasonic











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